# The SN54F299 is obsolete and no longer supplied.

## SN54F299, SN74F299 8-BIT UNIVERSAL SHIFT/STORAGE REGISTERS WITH 3-STATE OUTPUTS

SDFS071B - MARCH 1987 - REVISED APRIL 2004

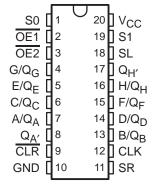
- Four Modes of Operation:
  - Hold (Store)
  - Shift Right
  - Shift Left
  - Load Data
- Operates With Outputs Enabled or at High Impedance
- 3-State Outputs Drive Bus Lines Directly
- Can Be Cascaded for N-Bit Word Lengths
- Direct Overriding Clear
- Applications:
  - Stacked or Pushdown Registers
  - Buffer Storage
  - Accumulator Registers

## description/ordering information

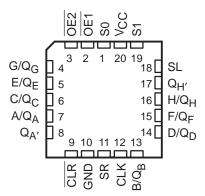
These 8-bit universal shift/storage registers feature multiplexed I/O ports to achieve full 8-bit data handling in a single 20-pin package. Two function-select (S0, S1) inputs and two output-enable (OE1, OE2) inputs can be used to choose the modes of operation listed in the function table.

Synchronous parallel loading is accomplished by taking both S0 and S1 high. This places the 3-state outputs in a high-impedance state and permits data that is applied on the I/O ports to

SN54F299 . . . J PACKAGE SN74F299 . . . DW, N, OR NS PACKAGE (TOP VIEW)



SN54F299 . . . FK PACKAGE (TOP VIEW)



be clocked into the register. Reading out of the register can be accomplished while the outputs are enabled in any mode. Clearing occurs when the clear (CLR) input is low. Taking either OE1 or OE2 high disables the outputs but has no effect on clearing, shifting, or storage of data.

#### ORDERING INFORMATION

TA	PACKAG	<sub>GE</sub> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 20	SN74F299N	SN74F299N
0°C to 70°C	Tube of 25		SN74F299DW	F000
0 0 10 70 0	SOIC - DW	Reel of 2000	SN74F299DWR	F299
	SOP - NS	Reel of 2000	SN74F299NSR	74F299

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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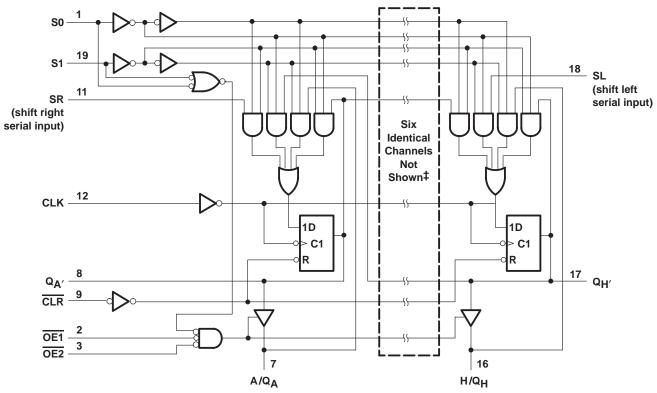
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#### **FUNCTION TABLE**

MODE				INP	UTS							I/O P	ORTS				OUTPUTS	
MODE	CLR	S1	S0	OE1†	OE2†	CLK	SL	SR	A/Q <sub>A</sub>	B/QB	C/QC	D/QD	E/Q <sub>E</sub>	F/Q <sub>F</sub>	G/Q <sub>G</sub>	H/Q <sub>H</sub>	$Q_{A'}$	$Q_{H'}$
	L	Χ	L	L	L	Χ	Χ	Χ	L	L	L	L	L	L	L	L	L	L
Clear	L	L	Χ	L	L	X	Χ	Χ	L	L	L	L	L	L	L	L	L	L
	L	Н	Н	X	X	Χ	Χ	X	Х	X	X	X	X	X	Χ	X	L	L
Hold	Н	L	L	L	L	Χ	Х	Χ	Q <sub>A0</sub>	Q <sub>B0</sub>	Q <sub>C0</sub>	Q <sub>D0</sub>	Q <sub>E0</sub>	Q <sub>F0</sub>	Q <sub>G0</sub>	Q <sub>H0</sub>	Q <sub>A0</sub>	Q <sub>H0</sub>
Поіа	Н	Χ	Χ	L	L	L	Χ	Χ	Q <sub>A0</sub>	Q <sub>B0</sub>	Q <sub>C0</sub>	$Q_{D0}$	Q <sub>E0</sub>	Q <sub>F0</sub>	Q <sub>G0</sub>	Q <sub>H0</sub>	Q <sub>A0</sub>	Q <sub>H0</sub>
Shift	Н	L	Н	L	L	1	Χ	Н	Н	Q <sub>An</sub>	Q <sub>Bn</sub>	QCn	Q <sub>Dn</sub>	Q <sub>En</sub>	Q <sub>Fn</sub>	QGn	Н	QGn
Right	Н	L	Н	L	L	$\uparrow$	Χ	L	L	$Q_{An}$	$Q_{Bn}$	QCn	$Q_{Dn}$	$Q_{En}$	$Q_{Fn}$	QGn	L	QGn
Shift	Н	Н	L	L	L	1	Н	Χ	Q <sub>Bn</sub>	QCn	Q <sub>Dn</sub>	Q <sub>En</sub>	Q <sub>Fn</sub>	QGn	Q <sub>Hn</sub>	Н	Q <sub>Bn</sub>	Н
Left	Н	Н	L	L	L	1	L	Χ	Q <sub>Bn</sub>	QCn	$Q_{Dn}$	Q <sub>En</sub>	Q <sub>Fn</sub>	$Q_{Gn}$	Q <sub>Hn</sub>	L	$Q_{Bn}$	L
Load	Н	Н	Н	Χ	Χ	1	X	Χ	а	b	С	d	е	f	g	h	а	h

NOTE: a . . . h = the level of the steady-state input at inputs A through H, respectively. This data is loaded into the flip-flops while the flip-flop outputs are isolated from the I/O terminals.

## logic diagram (positive logic)



‡ I/O ports not shown: B/QB (13), C/QC (6), D/QD (14), E/QE (5), F/QF (15), and G/QG (4).

<sup>†</sup> When one or both output-enable inputs are high, the eight I/O terminals are disabled to the high-impedance state; however, sequential operation or clearing of the register is not affected.

## SN54F299, SN74F299 8-BIT UNIVERSAL SHIFT/STORAGE REGISTERS WITH 3-STATE OUTPUTS

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	
Input current range	–30 mA to 5 mA
Voltage range applied to any output in the disabled or power-off state	–0.5 V to 5.5 V
Voltage range applied to any output in the high state	–0.5 V to V <sub>CC</sub>
Current into any output in the low state: QA' or QH'	40 mÅ
SN54F299 (Q <sub>A</sub> thru Q <sub>H</sub> )	40 mA
SN74F299 (Q <sub>A</sub> thru Q <sub>H</sub> )	48 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DW package	58°C/W
N package	69°C/W
NS package	60°C/W
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input voltage ratings may be exceeded provided the input current ratings are observed.

## recommended operating conditions (see Note 3)

			S	N54F29	9	SN74F299			LINIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
$V_{IH}$	High-level input voltage		2			2			V
$V_{IL}$	Low-level input voltage				0.8			0.8	V
lıK	Input clamp current				-18			-18	mA
	I Park Toward and an owner of	Q <sub>A</sub> ' or Q <sub>H</sub> '			- 1			- 1	4
ЮН	High-level output current	Q <sub>A</sub> thru Q <sub>H</sub>			-3			-3	mA
		Q <sub>A</sub> ' or Q <sub>H</sub> '			20			20	
lOL	Low-level output current	Q <sub>A</sub> thru Q <sub>H</sub>			20			24	mA
TA	Operating free-air temperature		-55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				S	N54F29	9	S	N74F299	)	
PA	ARAMETER	TES	r conditions	MIN	TYP†	MAX	MIN	TYP	MAX	UNIT
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
	Q <sub>A</sub> ' or Q <sub>H</sub> '		I <sub>OH</sub> = – 1 mA	2.5	3.4		2.5	3.4		
\/ - · ·	O . them. O .	V <sub>CC</sub> = 4.5 V	$I_{OH} = -1 \text{ mA}$	2.5	3.4		2.5	3.4		V
VOH	Q <sub>A</sub> thru Q <sub>H</sub>		IOH = -3  mA	2.4	3.3		2.4	3.3		V
	Any output	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -1 \text{ mA to } -3 \text{ mA}$				2.7			
	$Q_{A'}$ or $Q_{H'}$		$I_{OL} = 20 \text{ mA}$		0.3	0.5		0.3	0.5	
VOL	0 11	V <sub>CC</sub> = 4.5 V	$I_{OL} = 20 \text{ mA}$		0.3	0.5				V
Q <sub>A</sub> thru Q <sub>H</sub>		$I_{OL} = 24 \text{ mA}$					0.35	0.5		
	A thru H	V 55V	V <sub>I</sub> = 5.5 V			1			1	4
1 <sub>1</sub>	Any other	$V_{CC} = 5.5 \text{ V}$	V <sub>I</sub> = 7 V			0.1			0.1	mA
. +	A thru H	V 55V	V 07V			70			70	•
¹ <sub>IH</sub> ‡	Any other	$V_{CC} = 5.5 \text{ V},$	$V_{I} = 2.7 \text{ V}$			20			20	μΑ
	A thru H					-0.65			-0.65	
I <sub>IL</sub> ‡	S0 or S1	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.5 V			-1.2			-1.2	mA
	Any other					-0.6			-0.6	
IOS§		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 0	-60		-150	-60		-150	mA
Icc		V <sub>CC</sub> = 5.5 V,	See Note 4		68	95		68	95	mA

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

NOTE 4: ICC is measured with  $\overline{\text{OE1}}$ ,  $\overline{\text{OE2}}$ , and CLK at 4.5 V.

# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

				V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C 'F299		SN54	SN54F299		F299	UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency				70		65		70	MHz
	Dulan donation	CLK high or low		7		8		7		
t <sub>W</sub>	Pulse duration	CLR low	7		8		7		ns	
	Setup time before	S0 or S1	High or low	8.5		9.5		8.5		
t	CLK↑	A/Q <sub>A</sub> thru H/Q <sub>H</sub> , SR, or SL	High or low	5.5		6.5		5.5		ns
t <sub>su</sub>	Inactive-state setup time before CLK↑¶	CLR	High	7		13		7		113
	Hald time after CLICT	S0 or S1	High or low	0		0		0		
<sup>t</sup> h	Hold time after CLK↑	A/Q <sub>A</sub> thru H/Q <sub>H</sub> , SR, or SL	High or low	2	·	2	·	2		ns

 $<sup>\</sup>P$  Inactive-state setup time also is referred to as recovery time.

<sup>‡</sup> For I/O ports (QA thru QH), the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current.

<sup>§</sup> Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

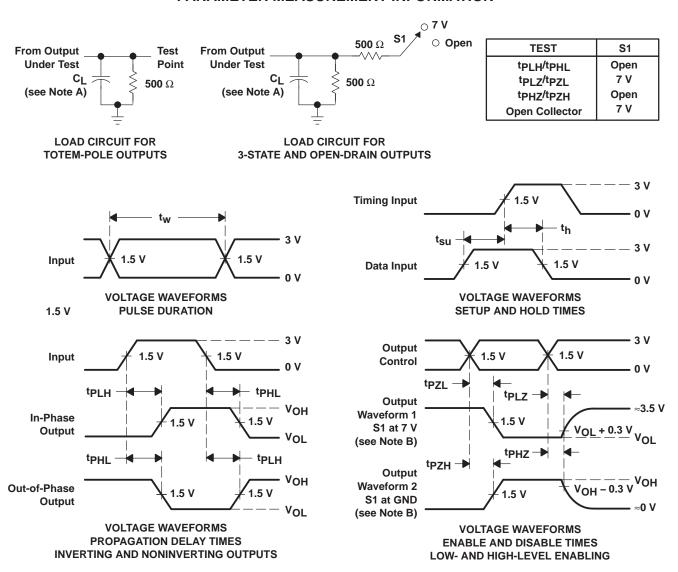
## switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5 \text{ V},$ $C_{L} = 50 \text{ pF},$ $R_{L} = 500 \Omega,$ $T_{A} = 25^{\circ}\text{C}$			$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$ $C_L = 50 \text{ pF},$ $R_L = 500 \Omega,$ $T_A = \text{MIN to MAX}^{\dagger}$				UNIT
			′F299		SN54F299		SN74F299			
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			70	100		65		70		MHz
t <sub>PLH</sub>	CLK	Q <sub>A′</sub> or Q <sub>H′</sub>	3.2	6.6	9	2.7	10.5	3.2	10	20
<sup>t</sup> PHL	CLK		2.7	6.1	8.5	2.2	10	2.7	9.5	ns
<sup>t</sup> PLH	CLK	Q <sub>A</sub> thru Q <sub>H</sub>	3.2	6.6	9	2.7	11	3.2	10	20
<sup>t</sup> PHL	CLK		4.2	8.1	11	3.7	12.5	4.2	12	ns
	CLR	$Q_{A'}$ or $Q_{H'}$	3.7	7.1	9.5	3.2	11.5	3.7	10.5	
<sup>t</sup> PHL	CLR	Q <sub>A</sub> thru Q <sub>H</sub>	5.7	10.6	14	5	15.5	5.7	15	ns
<sup>t</sup> PZH	OE1 or OE2	O . Albama O	2.7	5.6	8	2.2	10.5	2.7	9	
tPZL	OET OF OEZ	Q <sub>A</sub> thru Q <sub>H</sub>	3.2	6.6	10	2.7	12	3.2	11	ns
<sup>t</sup> PHZ	OE1 or OE2	Q <sub>A</sub> thru Q <sub>H</sub>	1.7	4.1	6	1.7	9	1.7	7	ns
<sup>t</sup> PLZ	OET OF OE2		1.2	3.6	5.5	1.2	7.5	1.2	6.5	115

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

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#### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50~\Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns, duty cycle = 50%.
- D. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



## PACKAGE OPTION ADDENDUM

10-Dec-2020

#### **PACKAGING INFORMATION**

www.ti.com

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74F299DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	F299	Samples
SN74F299DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	F299	Samples
SN74F299N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74F299N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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# **PACKAGE OPTION ADDENDUM**

10-Dec-2020

In no event shall TI's liabilit	y arising out of such information	exceed the total purchase	price of the TI part(s) a	at issue in this document sold by	TI to Customer on an annual basis.

## **PACKAGE MATERIALS INFORMATION**

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## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F299DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

www.ti.com 5-Jan-2022



#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F299DWR	SOIC	DW	20	2000	367.0	367.0	45.0

# PACKAGE MATERIALS INFORMATION

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### **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74F299DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74F299N	N	PDIP	20	20	506	13.97	11230	4.32

# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



#### NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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